- 8 A Continuous On-State Current
- 80 A Surge-Current
- Glass Passivated Wafer
- 400 V to 800 V Off-State Voltage
- Max I<sub>GT</sub> of 20 mA

# 

Pin 2 is in electrical contact with the mounting base.

MDC1ACA

### absolute maximum ratings over operating case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT		
	TIC116D		400		
Repetitive peak off-state voltage (see Note 1)	TIC116M	V	600	V	
	TIC116S	$V_{DRM}$	700	v	
	TIC116N		800		
	TIC116D		400		
Repetitive peak reverse voltage	TIC116M	V	600	V	
	TIC116S	V <sub>RRM</sub>	700		
	TIC116N		800		
Continuous on-state current at (or below) 80°C case temperature (see Note 2)	I <sub>T(RMS)</sub>	8	Α		
Average on-state current (180° conduction angle) at (or below) 80°C case temperature			5	Α	
(see Note 3)	I <sub>T(AV)</sub>	3	^		
Surge on-state current (see Note 4)			80	Α	
Peak positive gate current (pulse width ≤ 300 μs)	I <sub>GM</sub>	3	Α		
Peak gate power dissipation (pulse width ≤ 300 μs)	P <sub>GM</sub>	5	W		
Average gate power dissipation (see Note 5)	P <sub>G(AV)</sub>	1	W		
Operating case temperature range	T <sub>C</sub>	-40 to +110	°C		
Storage temperature range	T <sub>stg</sub>	-40 to +125	°C		
Lead temperature 1.6 mm from case for 10 seconds	T <sub>L</sub>	230	°C		

NOTES: 1. These values apply when the gate-cathode resistance  $R_{GK}$  = 1  $k\Omega$ 

- 2. These values apply for continuous dc operation with resistive load. Above 80°C derate linearly to zero at 110°C.
- 3. This value may be applied continuously under single phase 50 Hz half-sine-wave operation with resistive load. Above 80°C derate linearly to zero at 110°C.
- 4. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.
- 5. This value applies for a maximum averaging time of 20 ms.



# TIC116 SERIES SILICON CONTROLLED RECTIFIERS

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### electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER			TEST CONDIT	IONS	MIN			UNIT
I <sub>DRM</sub>	Repetitive peak off-state current	V <sub>D</sub> = rated V <sub>DRM</sub>	R <sub>GK</sub> = 1 kΩ	T <sub>C</sub> = 110°C			2	mA
I <sub>RRM</sub>	Repetitive peak reverse current	V <sub>R</sub> = rated V <sub>RRM</sub>	I <sub>G</sub> = 0	T <sub>C</sub> = 110°C			2	mA
I <sub>GT</sub>	Gate trigger current	V <sub>AA</sub> = 6 V	$R_L = 100 \Omega$	t <sub>p(g)</sub> ≥ 20 μs		5	20	mA
V <sub>GT</sub> Gate trigger voltage		$V_{AA} = 6 V$ $t_{p(g)} \ge 20 \mu s$	$R_L = 100 \Omega$ $R_{GK} = 1 k\Omega$	T <sub>C</sub> = - 40°C			2.5	
	Gate trigger voltage	$V_{AA} = 6 \text{ V}$ $t_{p(g)} \ge 20  \mu\text{s}$	$R_L = 100 \Omega$ $R_{GK} = 1 k\Omega$			0.8	1.5	V
		$V_{AA} = 6 \text{ V}$ $t_{p(g)} \ge 20  \mu\text{s}$	$R_L = 100 \Omega$ $R_{GK} = 1 k\Omega$	T <sub>C</sub> = 110°C	0.2			
I <sub>H</sub>	Holding current	$V_{AA} = 6 \text{ V}$ Initiating $I_T = 100 \text{ mA}$	$R_{GK} = 1 k\Omega$	T <sub>C</sub> = - 40°C			70	mA
		$V_{AA} = 6 \text{ V}$ Initiating $I_T = 100 \text{ mA}$	$R_{GK} = 1 k\Omega$				40	1117 (
V <sub>TM</sub>	Peak on-state voltage	I <sub>TM</sub> = 8 A	(see Note 6)				1.7	V
dv/dt	Critical rate of rise of off-state voltage	$V_D$ = rated $V_D$	I <sub>G</sub> = 0	T <sub>C</sub> = 110°C		100		V/µs

NOTE 6: This parameter must be measured using pulse techniques, t<sub>p</sub> = 300 µs, duty cycle ≤ 2 %. Voltage sensing-contacts, separate from the current carrying contacts, are located within 3.2 mm from the device body.

### thermal characteristics

PARAMETER			TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			3	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			62.5	°C/W

### resistive-load-switching characteristics at 25°C case temperature

	PARAMETER	TEST CONDITIONS			MIN	TYP	MAX	UNIT
t <sub>gt</sub>	Gate-controlled turn-on time	I <sub>T</sub> = 5 A	I <sub>G</sub> = 200 mA	See Figure 1		0.8		μs
tq	Circuit-commutated turn-off time	I <sub>T</sub> = 5 A	I <sub>RM</sub> = 10 A	See Figure 2		11		μs

### PARAMETER MEASUREMENT INFORMATION

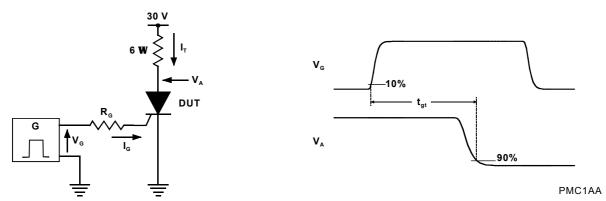
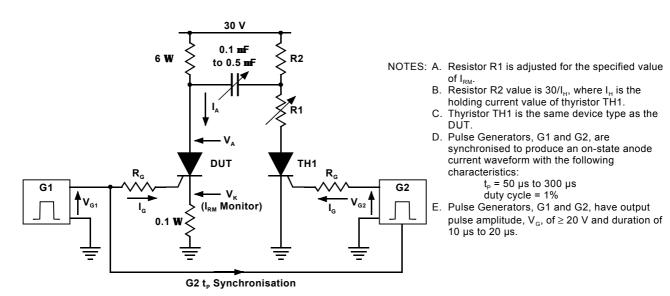


Figure 1. Gate-controlled turn-on time



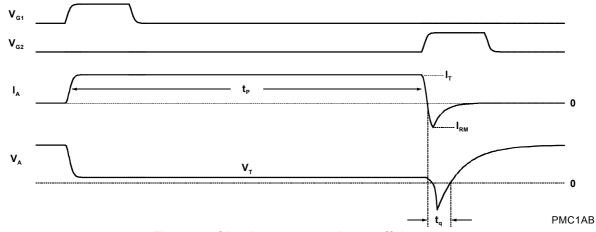
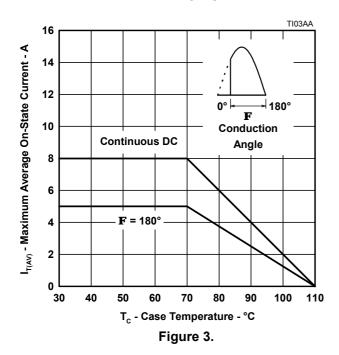


Figure 2. Circuit-commutated turn-off time



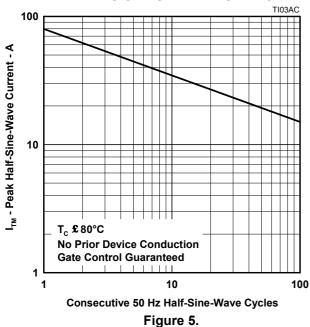
### TYPICAL CHARACTERISTICS

### **AVERAGE ON-STATE CURRENT DERATING CURVE**



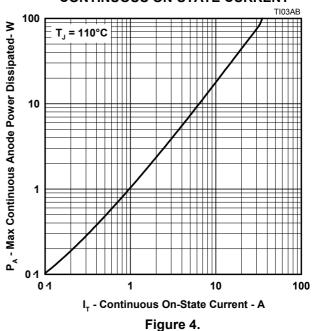
# **SURGE ON-STATE CURRENT**

### **CYCLES OF CURRENT DURATION**



# MAX CONTINUOUS ANODE POWER DISSIPATED

### **CONTINUOUS ON-STATE CURRENT**



# TRANSIENT THERMAL RESISTANCE

### CYCLES OF CURRENT DURATION

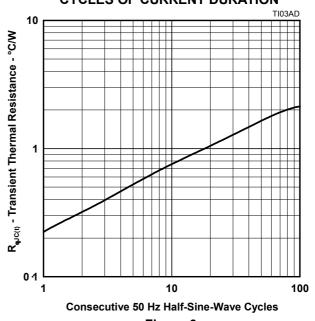


Figure 6.

### PRODUCT INFORMATION

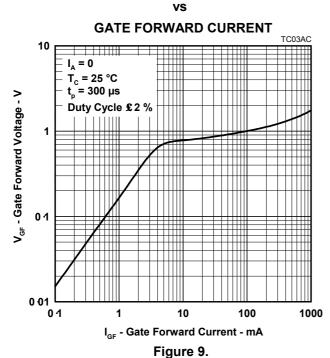
### **TYPICAL CHARACTERISTICS**

# GATE TRIGGER CURRENT vs

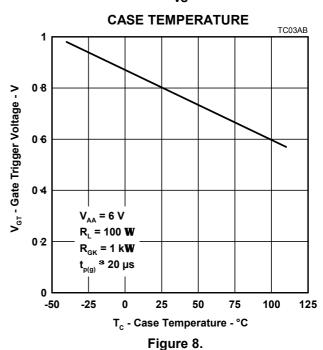
# CASE TEMPERATURE 10 V<sub>AA</sub> = 6 V R<sub>L</sub> = 1 kW t<sub>p(g)</sub> <sup>3</sup> 20 μs 1 -50 -25 0 25 50 75 100 125 T<sub>C</sub> - Case Temperature - °C

# GATE FORWARD VOLTAGE

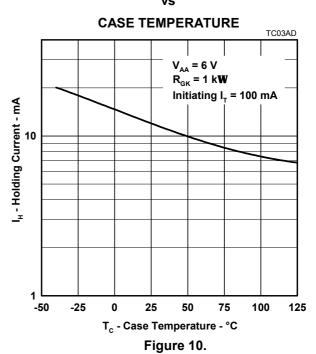
Figure 7.



# GATE TRIGGER VOLTAGE

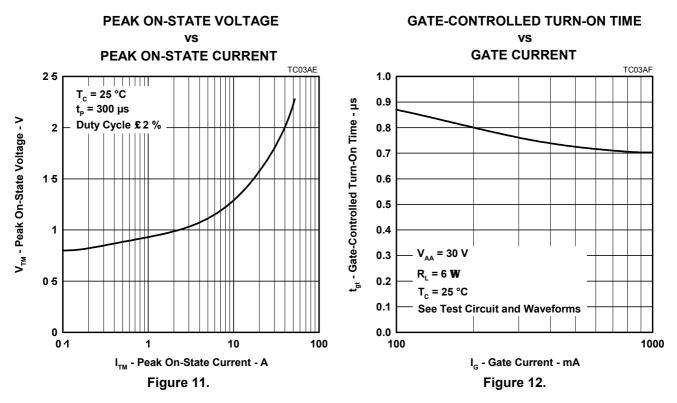


# HOLDING CURRENT vs

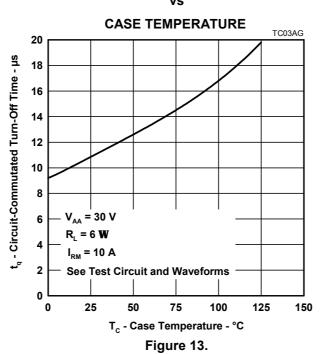




### **TYPICAL CHARACTERISTICS**



# CIRCUIT-COMMUTATED TURN-OFF TIME vs



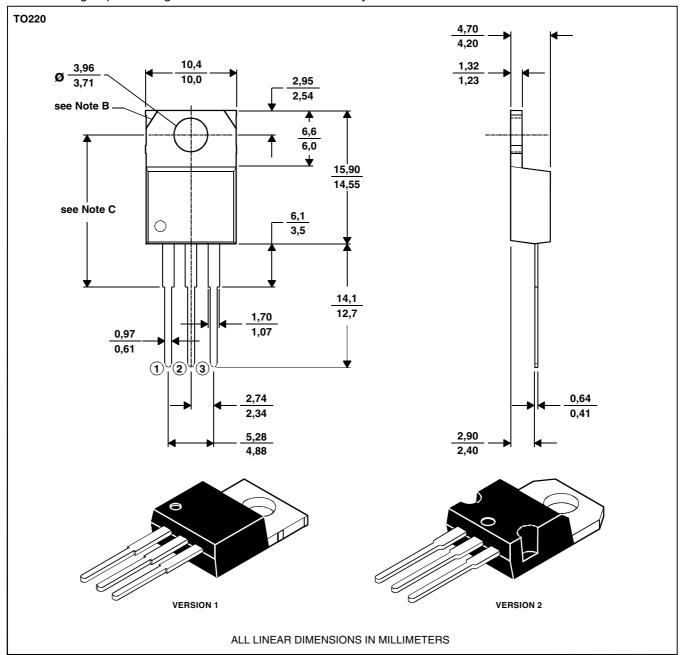
### PRODUCT INFORMATION

### **MECHANICAL DATA**

### **TO-220**

### 3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. The centre pin is in electrical contact with the mounting tab.

B. Mounting tab corner profile according to package version.

C. Typical fixing hole centre stand off height according to package version. Version 1, 18.0 mm. Version 2, 17.6 mm. **MDXXBE** 



# TIC116 SERIES SILICON CONTROLLED RECTIFIERS

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